

# Free Study Material from All Lab Experiments



**Solid-State Physics Notes  
for NET/GATE Physical Sciences  
# Semi-Conductors #**

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# SEMICONDUCTORS :-

Semiconductors are those materials whose conductivity lies b/w conductors and insulators.

In s/c conductivity can be controlled with the help of Doping (the addition of impurity in a controlled manner is called Doping.)

Ge was the first s/c brought in industry. Mostly Si & Ge s/c are used

Si is better than Ge :-

- Si has better thermal stability
- " " less reverse saturation current
- Mobility of  $e^-$ s in Si is greater than mobility of  $e^-$ s in Ge.

Mobility → Drift velocity of  $e^-$  / unit electric field is called Mobility.

band gap of Si & Ge ⇒ Si → 1.1 eV  
Ge → 0.7 eV

Silicon is the abundant material on the earth. Crust of the earth is made by  $SiO_2$ .

Si & Ge are indirect band gap s/c's, they can not be used in light emitting diode.

## Types of Semiconductors :-

(1) S/c can be divided acc. to their application,

(i) Elemental → Si, Ge, Sn etc.

(ii) Compound → GaAs, GaP, AlGaAs etc.

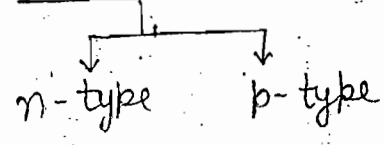
- If there is same type of s/c on both side of junc<sup>n</sup> Homojunction
- " " different " " " " Heterojunction



2) Semiconductors can be divided as

- (i) Intrinsic - Pure
- (ii) Extrinsic - Doped

Extrinsic s/c can be of 2 types

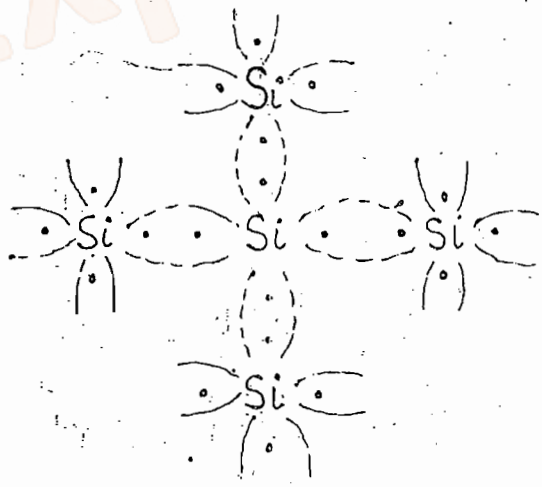


- (3) (i) Direct Band Gap s/c  
(ii) Indirect " "



### Intrinsic Semiconductor

- Si, Ge are the Intrinsic s/c.
- There are 4  $e^-$  in outermost orbit of Si & Ge.
- band gap of Si  $\rightarrow 1.1 \text{ eV}$
- " " Ge  $\rightarrow 0.7 \text{ eV}$
- Si has diamond cubic (dc) structure i.e. each Si atom is coordinated by 4 nearby Si atoms with sharing of  $1 e^-$  each.



• No  $e^-$  per Si atom is free. so it must fall in the category of insulator. But bcoz of small band gap, Si is a semiconductor.

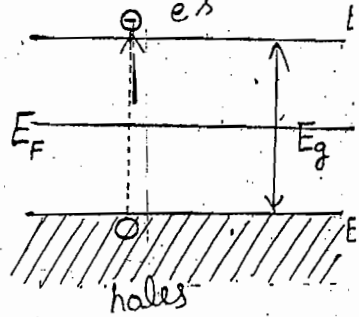
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At  $T=0K$ , No  $e^-$  is free. As  $T \uparrow$ , some  $e^-$  may be free but their conductivity will be very low so they are of No use.

- Minima of Conduction band  $\rightarrow E_c$
- Maxima of Valance band  $\rightarrow E_v$
- Gap b/w  $E_c$  &  $E_v$  is Energy band gap  $E_g$



At  $T=0K$ , Valance band is completely filled & conduction band is completely empty. & No  $e^-$  is free at  $T=0K$  so fermi level will be the level of 50% occupancy i.e. fermi-level will lie exactly in mid way of the completely filled & empty band.



If Temp  $\uparrow$  above  $T=0K$  i.e.  $T$  tends to room temp then some  $e^-$  may be free bcoz bond breaks. When  $e^-$  become free then it leave a vacancy. This vacancy is called Hole. An  $e^-$ -hole pair is called Excitons. & Excitons will follow B-E statistics.

In s/c,  $e^-$  will do motion in the conduction band & holes " " " " Valance "

• Charge of hole,  $+ve = +1.6 \times 10^{-19} C$

Effective mass of hole :-  $m_h^* > m_e^*$

i.e. hole is heavier than  $e^-$  bcoz  $e^-$  move freely but hole can not move freely, it'll move one by one

- Curvature of C.B.  $>$  Curvature of V.B.
- hole is a fermi particle.

In Intrinsic s/c,

$e^-$  & hole concentration will be same

$$n_i = p_i$$

$n_i \rightarrow$  no. of free  $e^-$  per unit volume

$p_i \rightarrow$  " " holes " " "

## Extrinsic Semiconductor :-

1) n type s/c :-

generally,  $m_h^* > m_e^*$

& Mobility  $\mu = \frac{e\hbar\tau}{m}$

$$\mu_h = \frac{e\hbar}{m_h^*} \quad \& \quad \mu_e = \frac{e\hbar}{m_e^*}$$



Because  $m_h^* > m_e^*$  so

$$\mu_e > \mu_h$$

So in n type s/c, -ve charge particles i.e. electrons are majority carriers.

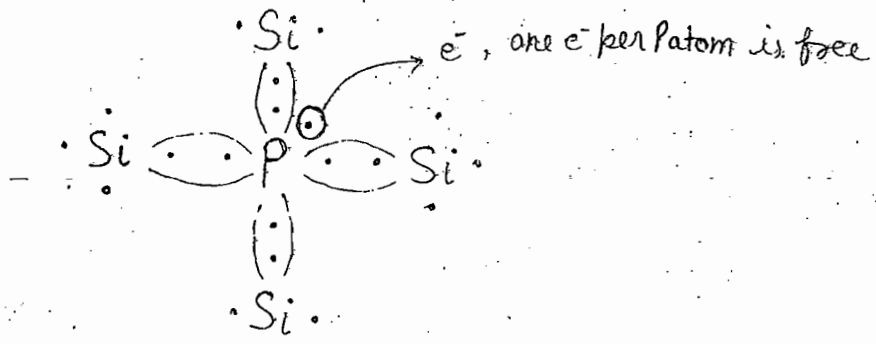
In p-type s/c, holes are majority carriers so n-type s/c is better than p-type s/c.

When a pentavalent impurity added to a pure <sup>Si</sup> semiconductor then it becomes n-type.

Ex of pentavalent impurity  $\rightarrow$  P, As, Sb, Bi etc.

Concentration of doping varies from 1 dopant atom per  $10^6$  to  $10^8$  atoms of Si

When 1 atom of phosphorus is at  $10^6$  Si atom then <sup>it is</sup> heavy doping as compare to 1 atom of P at  $10^8$  Si atom.



1  $e^-$  per P atom remains almost free, Not completely free

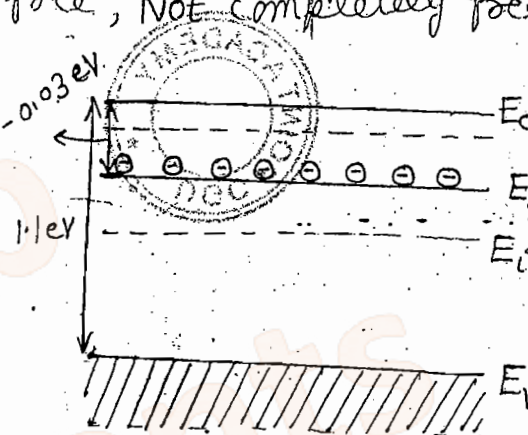
The level  $E_d$  is the level of 5th Phosphorus  $e^-$ .

Now fermi level is still b/w highest filled level & highest empty level.

fermi level lies b/w near to the conduction band.

Order of Energy b/w  $E_d$  &  $E_c = 0.01 - 0.03 \text{ eV}$

At room temp., all the  $e^-$ s of  $E_d$  will go in C.B. &  $e^-$ s become free.



for any s/c,  $np = n_i^2 \Rightarrow$  law of Mass action.

$n \rightarrow e^-$  concentration in doped s/c

$p \rightarrow$  hole " " " "

$n_i \rightarrow$  intrinsic carrier concentration.

n-type s/c is Neutral i.e. charge on n-type s/c = 0

{ In s/c,  $np = n_i p_i$  but in intrinsic s/c  $n_i = p_i$  do }  
 $np = n_i^2$

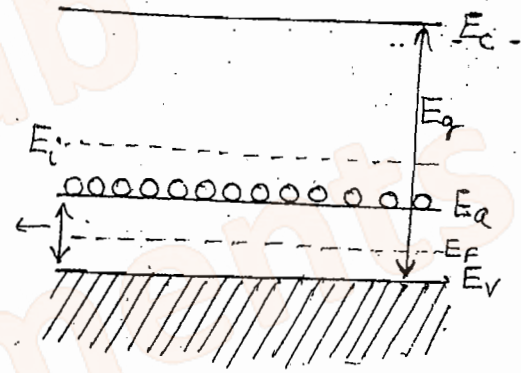
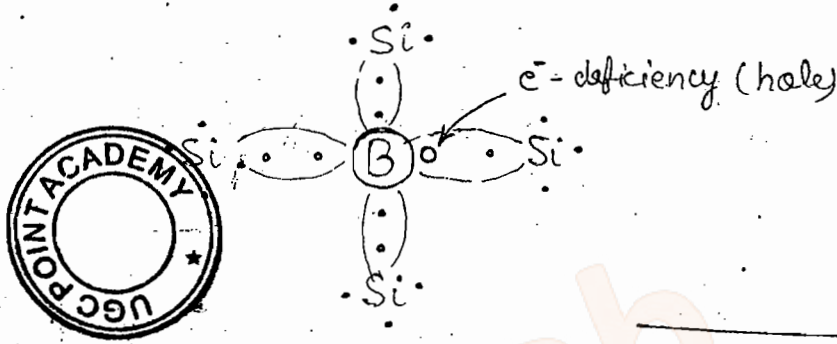
$E_i \rightarrow$  Intrinsic level in mid way of  $E_c$  &  $E_v$ .

https://alllabexperiments.com



## (2) P-type Semiconductor :-

p - means positive  $\Rightarrow$  holes are the majority charge carrier.  
 When a trivalent impurity like; B, Al, Ga, In etc. added in the Si s/c it behaves as a p-type s/c.



At room temp,  
 all the impurities are ionised.

An intrinsic s/c is doped with  $10^{16}$  Boron atom/cm<sup>3</sup>. Calculate the e<sup>-</sup> & hole concentration at 300K

Intrinsic carrier concentration  $n_i = 1.5 \times 10^{10} / \text{cm}^3$   
 hole p  $\approx N \approx 10^{16}$  B atom/cm<sup>3</sup>  
 concn.

e<sup>-</sup> concentration,  $n_p = n_i^2$

$$\Rightarrow n = \frac{n_i^2}{p} = \frac{(1.5 \times 10^{10})^2}{10^{16}}$$

$$n = \frac{2.25 \times 10^{20}}{10^{16}} = \underline{2.25 \times 10^4 / \text{cm}^3}$$

In p-type s/c, fermi level lies near the V.B.

E<sub>i</sub> is a fixed level, it lies b/w E<sub>v</sub> & E<sub>c</sub>.

\* If we dope  $\rightarrow$  Si on Ga site  $\rightarrow$  n type } This type of impurity is  
 (GaAs) Si " As "  $\rightarrow$  p type } Amphoteric impurity,  
 generally Si is doped on Ga site.

## Direct & Indirect band gap s/c :-

Direct Band Gap s/c :- In direct band gap s/c, bottom of the conduction band & top of the valence band lies at same value of  $k$ . In this,  $e^-$  can directly excite or deexcite by the absorption or emission of photon & there is no phonon involvement in the process of excitation or deexcitation.

If A photon incident of energy  $h\nu$ .

$h\nu > E_g$ , there is absorption

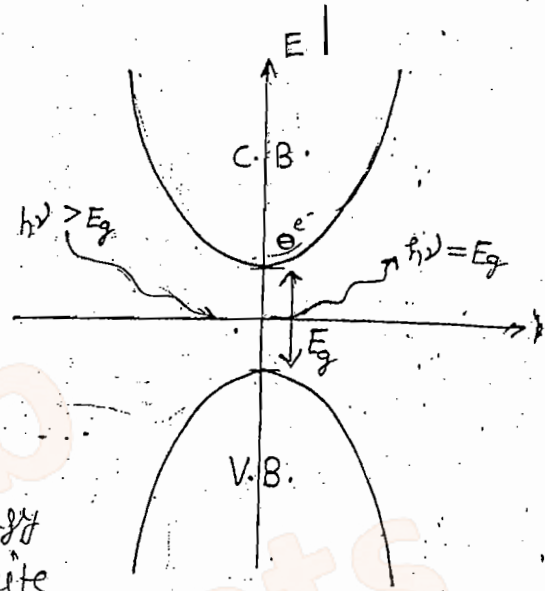
(&  $h\nu < E_g \rightarrow$  No absorption)

then  $e^-$  of V.B. will absorb this energy & excite to the C.B. & when it deexcite to V.B. then it will emit some energy i.e.  $h\nu = E_g$ .

There is no requirement of phonon or lattice in the conservation of energy & momentum.

Direct band gap s/cs are used in light emitting applications like LED & LASERS.

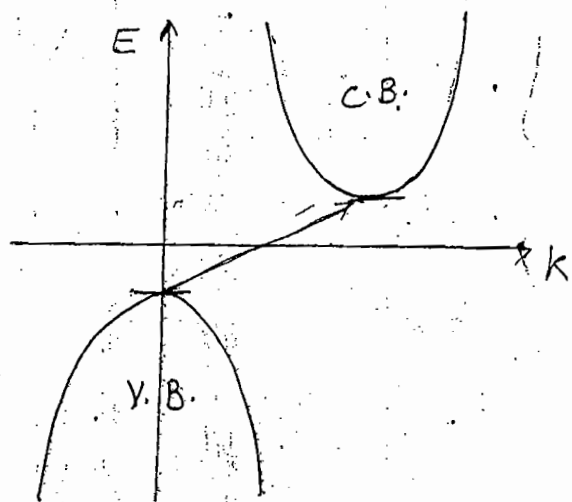
ex - GaAs, CdS, ZnS, CdSe etc.



Indirect Band Gap s/c :- In indirect band gap s/c, top of the V.B. & bottom of the C.B. lies at different values of  $k$ .

If  $e^-$  goes from top of the V.B. to bottom of the C.B., it has to change its energy as well as wave-vector  $k$ .

For mom. ( $\hbar k$ ) & energy conservation, there is involvement of phonon in the conservation process.





If there is excitation of  $e^-$ , then not all the energy will be emitted in form of photon but some energy is emitted in form of photons & some part in form of phonons. i.e. some part is transferred to the lattice & lattice will vibrate & heat generate.

So indirect band gap s/c is not suitable for light emission.

Ex - Si, Ge, GaP, SiC etc.

Q.

Equilibrium  $e^-$  & hole concentration in a s/c :-

$e^-$  concentration,  $n = N_c e^{-\frac{(E_c - E_f)}{kT}}$  — (1)

$N_c$  → Effective density of states at the C.B. edge

$$N_c = 2 \left( \frac{2\pi m_e^* k_B T}{h^2} \right)^{3/2}$$



$m_e^*$  → effective mass of  $e^-$

$E_c$  → Energy of C.B.

$E_f$  → Fermi energy

As Temp. ↑, exponential term is dominating so  $n$  ↑ exponentially

hole concentration;  $p = N_v e^{-\frac{(E_f - E_v)}{kT}}$  — (2)

$$N_v = 2 \left( \frac{2\pi m_h^* k_B T}{h^2} \right)^{3/2}$$

Multiply (1) × (2) ⇒

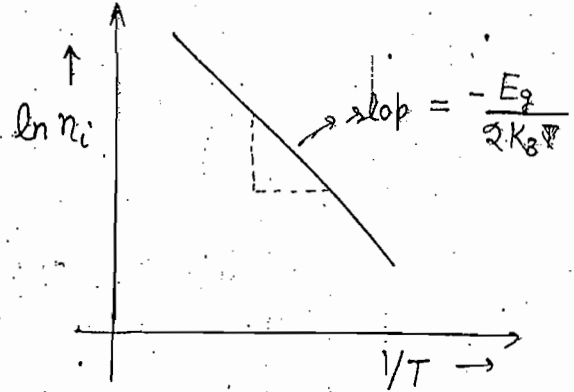
$$n_i^2 = np = N_c N_v e^{-\frac{(E_c - E_f)}{kT}} e^{-\frac{(E_f - E_v)}{kT}}$$

$$n_i = \sqrt{N_c N_v} \left[ e^{-\frac{E_c + E_f - E_f + E_v}{kT}} \right] = \sqrt{N_c N_v} e^{-(E_c - E_v)/kT}$$

$$(E_c - E_v = E_g)$$

$$n_i = 2 \left( \frac{2\pi K_B T}{h^2} \right)^{3/2} (m_e^* m_h^*)^{3/4} e^{-E_g/2K_B T}$$

$$\Rightarrow \ln n_i = \ln \left[ 2 \left( \frac{2\pi K_B T}{h^2} \right)^{3/2} \right] + \frac{3}{4} \ln(m_e^* m_h^*) - \frac{E_g}{2K_B T}$$



$$n = n_i e^{\left( \frac{E_F - E_i}{K_B T} \right)}$$

$$p = n_i e^{\left( \frac{E_i - E_F}{K_B T} \right)}$$

This  $n$  &  $p$  follow the law of mass action

Exact Position of Fermi level in a Semiconductor :-

In Intrinsic s/c :-  $n_i = p_i$

$$\Rightarrow N_c e^{-\frac{(E_c - E_F)}{K_B T}} = N_v e^{-\frac{(E_F - E_v)}{K_B T}}$$



$\therefore m_h^+ > m_e^*$  Hence  $\frac{N_v}{N_c} > 1$

$$\therefore e^{\left( \frac{-E_c + E_F + E_F - E_v}{K_B T} \right)} = \frac{N_v}{N_c} = \frac{2 \left( \frac{2\pi m_h^+ K_B T}{h^2} \right)^{3/2}}{2 \left( \frac{2\pi m_e^* K_B T}{h^2} \right)^{3/2}} = \left( \frac{m_h^+}{m_e^*} \right)^{3/2}$$

$$\Rightarrow e^{\frac{-E_v - E_c + 2E_F}{K_B T}} = \left( \frac{m_h^+}{m_e^*} \right)^{3/2}$$

Taking log,  $-\frac{E_v - E_c + 2E_F}{K_B T} = \ln \left( \frac{m_h^+}{m_e^*} \right)^{3/2}$

$$\frac{2E_F}{K_B T} = \frac{E_c + E_v}{K_B T} + \frac{3}{2} \ln \left( \frac{m_h^+}{m_e^*} \right)$$

$$2E_F = E_c + E_v + \frac{3}{2} K_B T \ln \left( \frac{m_h^+}{m_e^*} \right)$$

$$E_F = \left( \frac{E_c + E_v}{2} \right) + \frac{3K_B T}{4} \left( \frac{m_h^*}{m_e^*} \right)^{3/2}$$

At  $T=0K$ ,  $E_F = \frac{E_c + E_v}{2}$

Fermi level does not depend upon  $m_e^*$  &  $m_h^*$  But at fermi temp. it depend on  $m_e^*$  &  $m_h^*$

If temp.  $\uparrow$ , then fermi level is slightly moves in upward dir<sup>n</sup> but this movement is negligible. It can be neglected at room temp.

N-Type s/c :-

$$E_F = \frac{E_d + E_c}{2} + \frac{K_B T}{2} \ln \left( \frac{N_d}{N_c} \right)$$



Where,  $E_d \rightarrow$  donor level energy  
 $N_d \rightarrow$  " " concentration

As temp.  $\uparrow$ , then intrinsic carrier conc  $n_i \uparrow$  exponentially.  
 As  $n_i \uparrow$ , fermi level moves in downward dir<sup>n</sup>.  $\left[ \ln \left( \frac{N_d}{N_c} \right) < n_i \right]$

& when  $n_i = N_d$  then s/c will behave like Intrinsic s/c.  
 then fermi level move to mid way.

P-Type s/c

$$E_F = \frac{E_a + E_v}{2} - \frac{K_B T}{2} \ln \left( \frac{N_a}{N_v} \right)$$

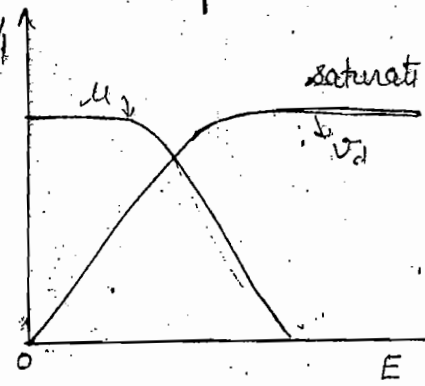
Variation of drift velocity with applied electric field in a s/c :-

drift velocity  $V_d = \mu E \Rightarrow \boxed{V_d \propto E}$

$\mu \rightarrow$  mobility

https://allabexperiments.com

Hence drift vel.  $v_d \uparrow$  with applied field linearly  
 for large values of  $E$ ,  $v_d$  become constant.



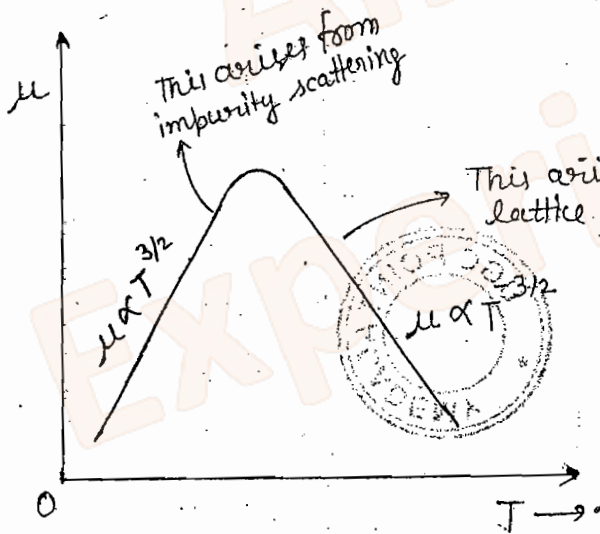
On applying more ele. field, energy will transfer to the lattice instead of  $v_d$ .

Mobility is just the slope of this graph.

Graph of mobility is 1st constant & then  $\downarrow$  to 0.



### Temperature Variation of Mobility:



Initially, when impurities are not ionised, we don't get mobility.

If  $e^-$  scatter from phosphorus atom then it is impurity sca. & if  $e^-$  scatter from Si atom then it is lattice sca.

$e^-$  will help to ionise the impurity.

[ P  $\rightarrow$  impurity  
 Si  $\rightarrow$  lattice

At Room temp., Mobility will be  $\mu \propto T^{-3/2}$   
 bcoz at room temp., all the impurities will be ionised

$\mu = \frac{e\tau}{m}$ , at high temp., lattice will vibrate more frequently so  $\tau \downarrow$  so  $\mu \downarrow$ .

https://alllabexperiments.com

# Temperature Variation of Conductivity in a Semiconductor:-

Doped s/c,  $\sigma = ne\mu_e + pe\mu_h$

If it is n-type,  $n \gg p$

$$\sigma = ne\mu_e + \frac{n_i^2}{n} e\mu_h$$

$\sigma \approx ne\mu_e$
$\sigma \approx pe\mu_h$

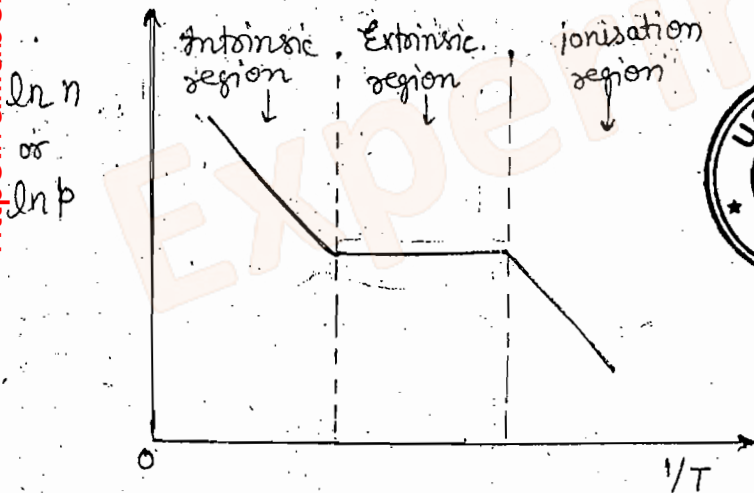
If p-type

Temp. dependence of conductivity  $\sigma$  is decided by  $e^-$  conc. & mobility.

no. of free  $e^-$ /unit vol.,  $n = N_d e^{-\frac{(E_c - E_d)}{KT}}$

donors exponentially ionise with temp.

$(E_c - E_d) \rightarrow$  donor ionisation energy



When temp. is so high that  $n_i \rightarrow n$

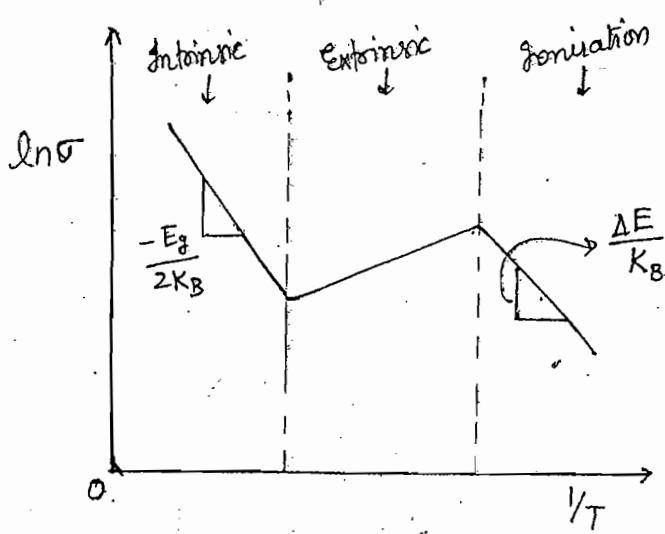
$$n_i \propto e^{-E_g/2KT}$$



All the s/c devices works in extrinsic region bcoz on  $\uparrow$  temp. there should be no variation with  $e^-$  conc.

For  $\sigma$  variation, combine the variation of  $n$  with  $\mu$ .

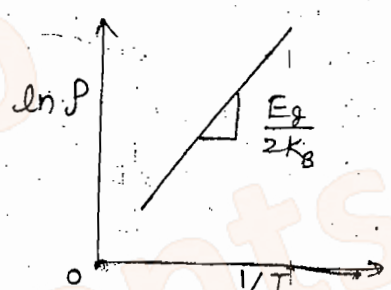
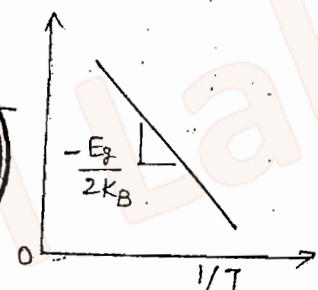
$$\sigma = ne\mu_e$$



acceptor ionization  
 p-type  $\Delta E = E_a - E_f$   
 Donor ionization energy  
 n-type,  $\Delta E = E_d - E_f$

If graph b/w ( $\ln P$  &  $1/T$ ) then slope =  $+\frac{E_g}{2K_B}$  in intrinsic region

for intrinsic s/c

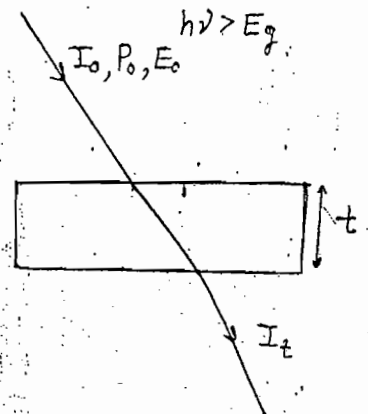


The information of band gap is obtained only in intrinsic region.

### Transmitted Power, Intensity, Energy through a semi-conducting crystal :-

Suppose we have a semi-conducting crystal of thickness  $t$ . A light wave of intensity  $I_0$  & power  $P_0$ , incident on it. [Power  $\rightarrow$  Intensity per unit area]

If  $h\nu > E_g$  then some part of the power will be absorbed & some will be transmitted.



$$I_a + I_t = I_0$$

Here, in s/c, absorbance + Transmittance = 1.

$$A + T = 1$$

(generally  $R + T = 1$ )

$$I_t = I_0 e^{-\alpha t}$$

$$P_t = P_0 e^{-\alpha t}$$

$\alpha$  → absorption coefficient  
 $t$  → thickness of the crystal  
 $I_0$  → incident intensity  
 $I_t$  → Transmitted "

Absorbed Intensity  $I_a = I_0 - I_t = I_0 (1 - e^{-\alpha t})$



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If  $h\nu < E_g$  then No absorption

$$I_a = 0$$

All the Intensity (light) will be transmitted

$$I_t = I_0$$

coz this photon is not capable to generate e-hole pair.

### Quantum Efficiency :-

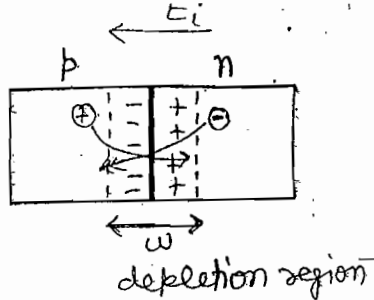
100% Quantum efficiency means, each photon absorbed create 1 e<sup>-</sup> & 1 hole.

60% Q. efficiency means, only 60% photon, from 100% are absorbed capable to generate e-hole pair.

Quantum efficiency is the measurement of <sup>betterness of</sup> light emitting device.

### p-n Junction :-

p-n junc<sup>n</sup> is a combination of two types of semiconductors p & n type. This is formed within the single s/c, on one side we have acceptor impurity, on the other side we have donor impurity. #



Due to concentration gradient, there will be diffusion.

Holes will diffuse from  $p \rightarrow n$   
 $e^-$  " " " "  $n \rightarrow p$ .

Due to diffusion  $e^-$  from n side will leave behind the immobile +ve ion core & Holes from p side will leave behind the -ve ion core.

n side is +vely charged & p side is -vely charge & But junction as a whole is neutral.

depletion region is depleted of free (mobile) charge carriers & width of depletion region is  $w$ . Its typical order is  $1 \mu m$ .

Due to the flow of  $e^-$  & holes there will flow diffusion current.

$I_n$  (diffusion)  $\rightarrow p \rightarrow n$

$I_p$  (diffusion)  $\rightarrow p \rightarrow n$

Net diffusion current  $\rightarrow p \rightarrow n$



There is a internal electric field in depletion region,  $E_i$ . It will oppose the diffusion. It will try to stop the diffusion. It will help the minority charge carriers to cross the junc<sup>n</sup>.

The motion under this electric field is drift motion &

$I_n$  (diff) there will be drift current

$I$

$I_n$  (drift) =  $n \rightarrow p$

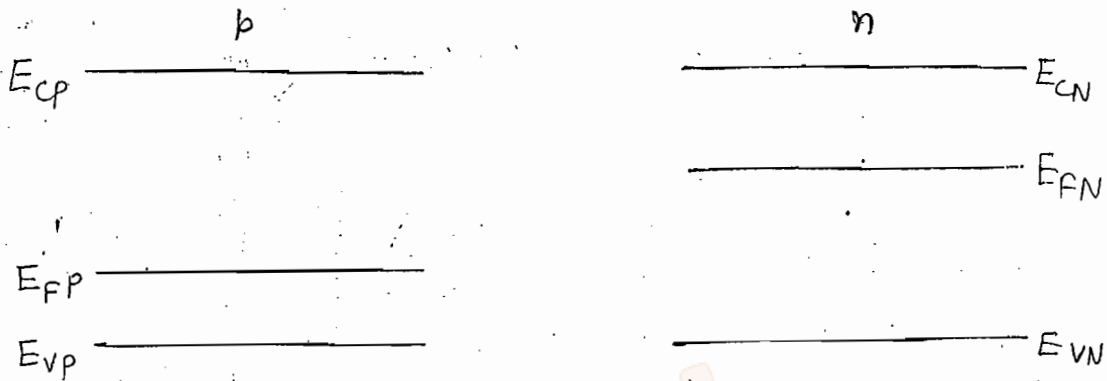
$I_p$  (drift) =  $n \rightarrow p$

Net current is zero as no external force is applied



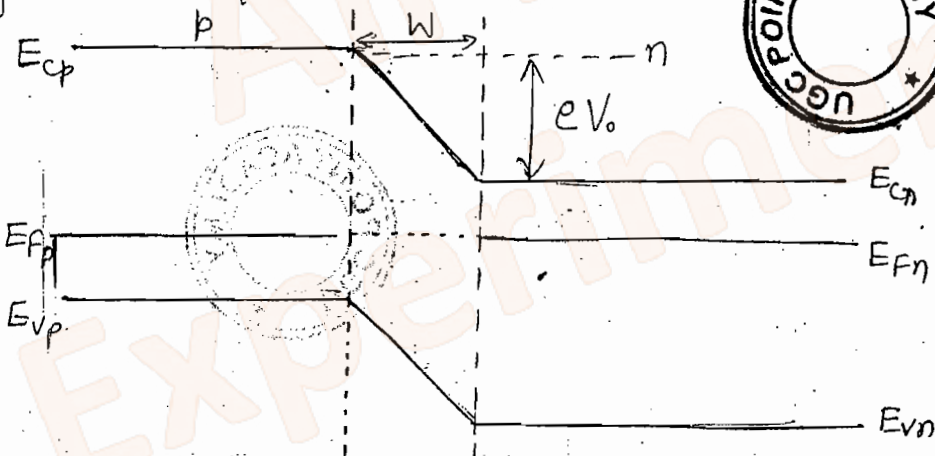
$$I_n(\text{diff.}) + I_n(\text{drift}) = 0$$

$$I_p(\text{diff.}) + I_p(\text{drift}) = 0$$



Fermi-level 'll act as a reference level.

If we join two s/c then their fermi level will be aligned at equilibrium.



The pot<sup>n</sup> of Elec. field  $E$  is called contact pot<sup>n</sup>  $V_0$ .  
 (This  $\Rightarrow$   $E$  field is caused by coming in contact p & n type s/c.)  
 This contact pot<sup>n</sup>  $V_0$  is the characteristic property of the jee<sup>n</sup>.

Energy barrier  $\rightarrow eV_0$

$V_0$  depends on temp & doping concentration on both the sides.

$V_0 = \frac{KT}{e} \ln\left(\frac{p_p}{p_n}\right)$
$V_0 = \frac{KT}{e} \ln\left(\frac{n_n}{n_p}\right)$

$p \rightarrow$  conc. of holes i.e. hole conc. on p side  
 $p \rightarrow$  type

$p_n \rightarrow$  hole conc. on n side

$n_n \rightarrow e^-$  " " n "

$n_p \rightarrow e^-$  " " p "

# If p side & n side are doped by  $N_a$  &  $N_d$  then

$$p_p \approx N_a$$

$$n_n \approx N_d$$

$$p_n = \frac{n_i^2}{N_d}$$

$$n_p = \frac{n_i^2}{N_a}$$



$$\left\{ \begin{aligned} p_n n_n &= n_i^2 \\ p_p n_p &= n_i^2 \\ p_n &= \frac{n_i^2}{n_n} = \frac{n_i^2}{N_d} \\ n_p &= \frac{n_i^2}{p_p} = \frac{n_i^2}{N_a} \end{aligned} \right.$$

$$V_o = \frac{kT}{e} \ln \left( \frac{N_a}{n_i^2/N_d} \right)$$

$$V_o = \frac{kT}{e} \ln \frac{N_a N_d}{n_i^2}$$

Contact pot<sup>n</sup> depends upon doping concentration.

# If doping conc. is heavy (i.e. j<sub>ue</sub><sup>n</sup> is heavily doped) then  $V_o$  will be more.

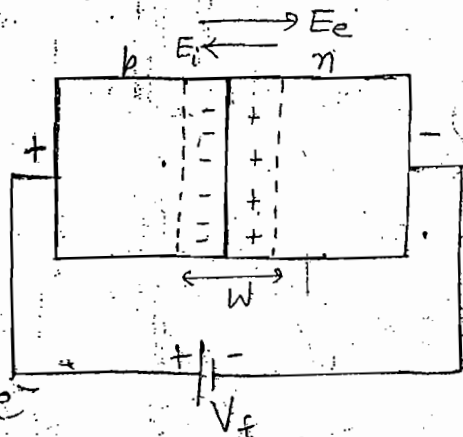
P-n J<sub>ue</sub><sup>n</sup> under forward bias :-

pot<sup>n</sup> at p side  $\rightarrow +ve$

" " n "  $\rightarrow -ve$

External e. field will be p  $\rightarrow$  n  
 by external e. field, strength of the internal e. field will  $\downarrow$

so barrier height will  $\downarrow$  then  $e^-$  will easily cross the barrier so  $e^-$  can move from C.B. of n side to C.B. of p side.



holes from V.B. of p side can move to V.B. of n side

$I_n$  (diffusion)  $\uparrow$

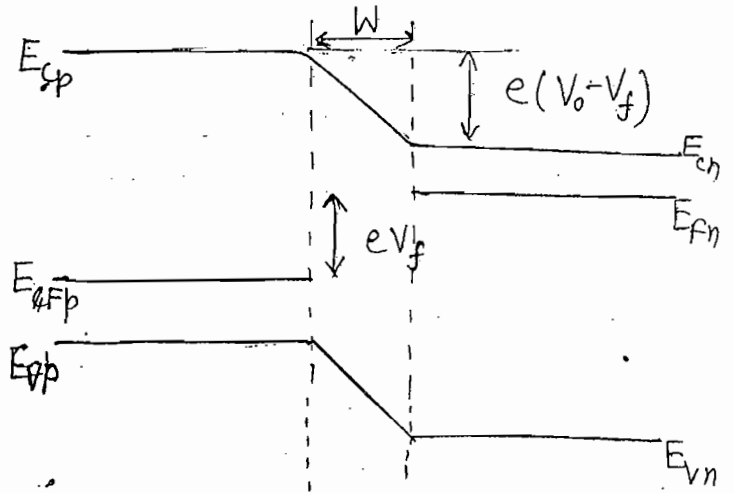
$I_p$  (diffusion)  $\uparrow$

So Total diffusion current  $\uparrow$

Depletion region width.

$w \downarrow$

Pot<sup>n</sup> developed by  $E_i$  is shielded by the pot<sup>n</sup> developed by  $E_e$ .



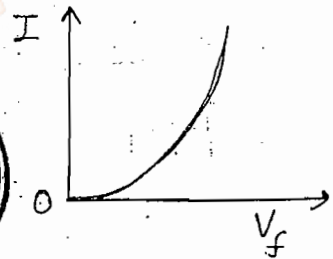
Current flowing from p  $\rightarrow$  n  $\Rightarrow$  forward current

n  $\rightarrow$  p  $\Rightarrow$  Reverse "

In F.B., Net current flow from p  $\rightarrow$  n. There is no effect on reverse current.

Reverse current is due to minority carriers. At low voltage minority carrier is independent of applied voltage.

In F.B., Current  $\uparrow$  exponentially with forward voltage (applied)



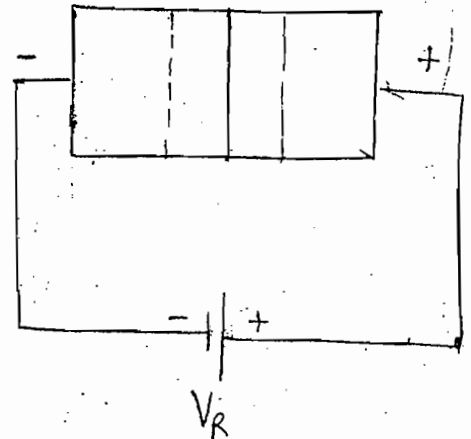
P-n junc<sup>n</sup> under Reverse Bias :-

External  $E$  field will be in dir<sup>n</sup> of internal  $E$  field. Diffusion will be completely stopped.

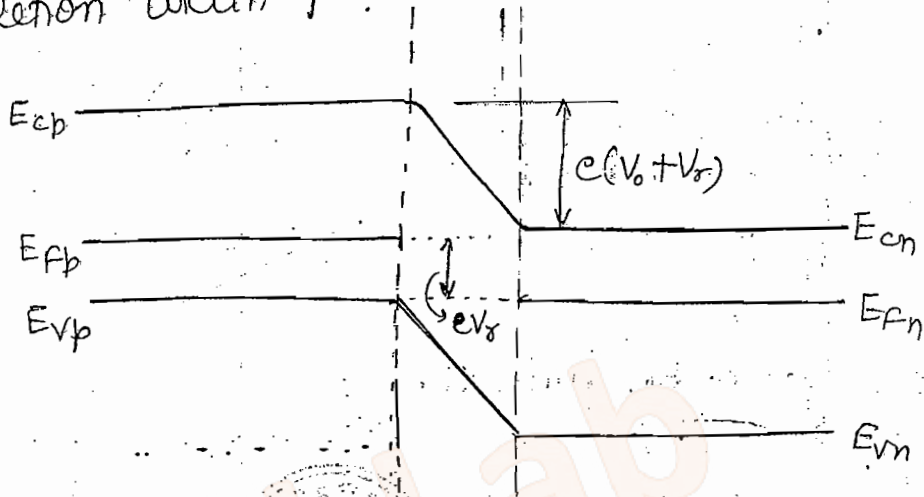
Barrier height  $\uparrow$

Hence diffusion of  $e^-$  & holes would become impossible.

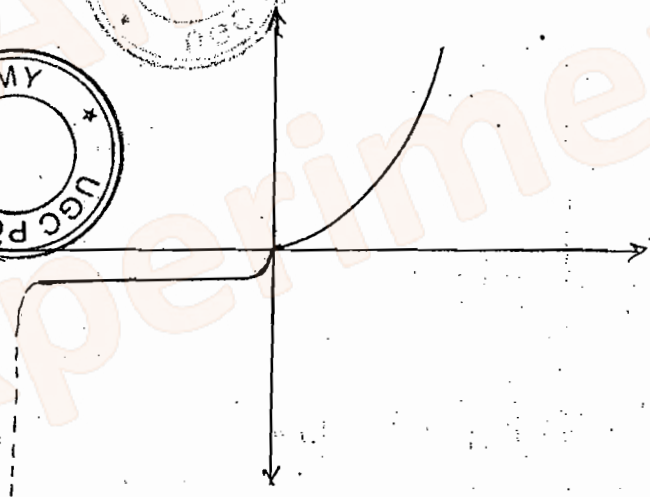
Diffusion Current = 0



Drift current effect on reverse current ( $n \rightarrow p$ )  $\Rightarrow$   
 No effect i.e. Reverse current will be same as it depend  
 on minority carrier conc. & independent of applied vol.  
 depletion width  $\uparrow$

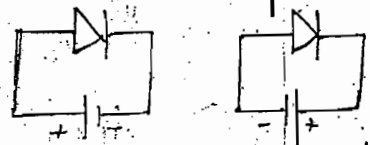


I-V characteristic,



Reverse current is constant with applied voltage until very high voltage is applied. If vol. is high then junction will breakdown (Zener diode).

Diode is design s.t. if F.B. then there will be current flow with small resistance i.e. current is small large.  
 & in R.B., current flow, (minority current flow with high resistance. current is small)



This is a rectifying property.

Diode will behave as a Rectifier.

(Minority current is large in Ge & Ge is less thermal stable)

space

## Step charge at the Junction:-

Extension of depletion layer on n side is  $x_{n0}$  & on p side is  $x_{p0}$ .

$$\text{So } \boxed{x_{n0} + x_{p0} = W} \quad \text{--- (1)}$$

As  $\text{ju}^e$  as a whole is neutral

$$\text{So } |\Phi_-| = \Phi_+$$

$N_d$   $\rightarrow$  donor conc. per unit vol.

$N_a$   $\rightarrow$  acceptor " " " " " "

$$\Phi_+ = e N_d x_{n0} A$$

$$\Phi_- = e N_a x_{p0} A$$

$$\text{So } e N_d x_{n0} A = e N_a x_{p0} A$$

$$\Rightarrow \boxed{N_d x_{n0} = N_a x_{p0}} \quad \text{--- (2)}$$

So depletion layer <sup>width</sup> extension will be more on lightly doped side

$$\text{If } N_d = 10^{17} \text{ P atoms/cm}^3, N_a = 10^{16} \text{ B atoms/cm}^3$$

$$\text{then } x_{p0} > x_{n0}$$

So depletion layer width is more on lightly doped side.

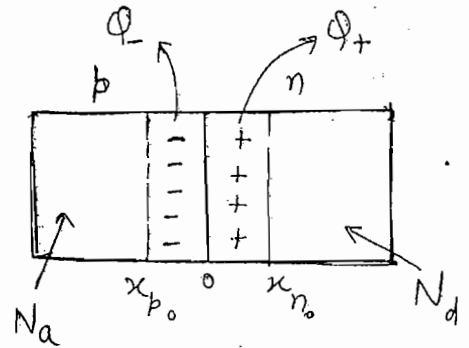
from (1) & (2),

$$(1) \Rightarrow x_{n0} = W - x_{p0}$$

$$(2) \Rightarrow N_d (W - x_{p0}) = N_a x_{p0}$$

$$- N_d x_{p0} - N_a x_{p0} = - N_d W$$

$$\boxed{x_{p0} = \frac{W N_d}{N_d + N_a}}$$



$$x_{n_0} = W - \frac{W N_d}{N_a + N_d} = \frac{W N_a + W N_d - W N_d}{N_d + N_a}$$

$$x_{n_0} = \frac{W N_a}{N_a + N_d}$$

Maximum

Electric field in the depletion region :-

It is given by

$$E_0 = -\frac{e}{\epsilon} N_d x_{n_0} = -\frac{e}{\epsilon} N_a x_p$$

$\epsilon \rightarrow$  permittivity of the material

The value of electric field at junc<sup>n</sup>  $\rightarrow E_0$

$E_0$  depend on permittivity, doping conc., extension of depletion region

Depletion Region Width W :-

$$W = \left[ \frac{2 \epsilon (V_0 - V)}{e} \left( \frac{N_a + N_d}{N_a N_d} \right) \right]^{1/2}$$



If doping conc.  $N_a, N_d \uparrow$  then  $W \downarrow$

In F.B.,  $V = V_f$ ,  $W \downarrow$

In R.B.,  $V = -V_r$ ,  $W \uparrow$

Effect of Temperature :-

If No Bias is applied, If  $T \uparrow$ ,  $W \uparrow$

$$W \propto (T)^{1/2}$$

$$V_0 = \frac{kT}{e} \ln \left( \frac{N_a N_d}{n_i^2} \right)$$

## Capacitance of p-n junc<sup>n</sup>

There are 2 types of capacitances associated with p-n junc<sup>n</sup>

1) Junction capacitance :- This is due to immobile (cant move) +ve & -ve charges in the junc<sup>n</sup>. This is forming a parallel plate capacitor. This is also called Depletion region capacitance.

This is dominant under reverse bias and

$$C_j = \frac{\epsilon A}{W}$$

In free space  $\epsilon \rightarrow \epsilon_0$

A  $\rightarrow$  cross sectional area of the diode.

$$C_j \propto \frac{1}{W}$$

$$C_j \propto (V_0 - V)^{-1/2}$$



2) Charge Storage Capacitance :- This is arising from stored charges on p & n side. This is also called diffusion capacitance. This is dominant under forward bias.

$$C_d = \frac{1}{3} \frac{e^2}{k_B T} A l n_p e^{eV/k_B T}$$

l  $\rightarrow$  diffusion length

V  $\rightarrow$  applied voltage

$$C_d \propto e^{eV/k_B T}$$

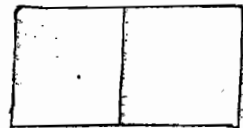
exponential dependancy on V

If V  $\rightarrow$  -ve,  $C_j$  is dominating (R.B.)

V  $\rightarrow$  +ve,  $C_d$  is dominating (F.B.)

Diffusion Length :- It may be defined for hole as well as for  $e^-$ . ( $L_p, L_n$ ). This is the average distance travelled by  $e^-$  or hole before the recombination. If any  $e^-$  diffuse from n to p side the diffusion length is measured on p side.

holes, diffusion length measured on n side.



Diffusion length is defined in the opposite region.

$$L_p = \sqrt{D_p \tau_p}$$

$$L_n = \sqrt{D_n \tau_n}$$

Where,  $D_p, D_n \rightarrow$  diffusion coefficient of hole &  $e^-$

$\tau_p, \tau_n \rightarrow$  relaxation time of hole &  $e^-$



Einstein Relation for a semiconductor :-

$$\frac{D}{\mu} = \frac{k_B T}{e}$$

Ratio of diffusion coefficient & mobility

Einstein relation is independent of particular type of charge carrier. i.e.

$$\frac{D_n}{\mu_n} = \frac{D_p}{\mu_p} = \frac{k_B T}{e}$$



Diode Equation :- Relation b/w diode voltage & diode current

$$I = eA \left( \frac{D_p}{L_p} p_n + \frac{D_n}{L_n} n_p \right) \left( e^{\frac{eV}{k_B T}} - 1 \right)$$

$e \rightarrow$  electronic charge

$A \rightarrow$  cross-sectional area

$D_p, D_n \rightarrow$  diffusion coefficient

$L_n, L_p \rightarrow$  " length

$p_n, n_p \rightarrow$  hole conc. of n side,  $e^-$  conc. of p side



$$I = I_0 \left( e^{\frac{eV}{k_B T}} - 1 \right)$$

In F.B.  $V = V_f \Rightarrow I_f = I_0 e^{\frac{eV}{k_B T}}$

( $e^{eV/k_B T}$  term dominates)

forward current  $\uparrow$  exponentially with voltage.

In R.B.  $V = -V_r \Rightarrow I_{pr} = I_0$

reverse current is independent on applied voltage.

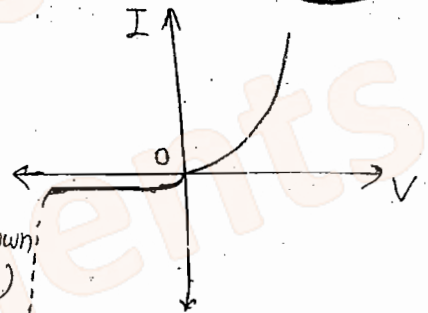


## Zener Breakdown & Avalanche Breakdown:

Zener Breakdown <sup>Current</sup> :- Reverse current is

almost independent of applied reverse voltage but if reverse voltage is very high so that it can break the covalent bonds then due to generation of large no. of e<sup>-</sup>-hole

pairs reverse current increases very sharply. This current is called Breakdown Current. Breakdown can occur by two mechanism



- (i) Zener
- (ii) Avalanche

### Zener breakdown :-

- (i) Zener breakdown occurs in heavily doped junction
- (ii) " " " voltage is low.
- (iii) " " " voltage decreases as temp. increases,
- (iv) Zener effect is field ionisation of host atoms at the junction.

W (width of d. region) is small so that e<sup>-</sup> & holes directly tunnel from one side to another.

## Avalanche Breakdown

- (i) Avalanche breakdown occurs in lightly doped junction
- (ii) " " voltage is high.
- (iii) " " voltage increases as temp increases.
- (iv) " " occurs due to impact ionisation of host atoms by highly accelerated  $e^-$ s.

Here  $W$  is large so  $e^-$  can not tunnel but highly accelerated  $e^-$  scattered with atoms & bond break so impact ionisation, impact of  $e^-$  ionisation occur due to scattering.

